

Title (en)

ELECTROLYTIC SOLUTION FOR ELECTROCHEMICAL DEPOSITION OF GOLD AND ITS ALLOYS

Title (de)

ELEKTROLYTISCHES BAD ZUM ELEKTROCHEMISCHEN ABSCHIEDEN VON GOLD UND GOLBLEGIERUNGEN

Title (fr)

BAIN ELECTROLYTIQUE POUR LE DEPOT ELECTROCHIMIQUE DE L'OR ET DE SES ALLIAGES

Publication

EP 1423557 A1 20040602 (FR)

Application

EP 02774881 A 20020822

Priority

- FR 0202922 W 20020822
- FR 0111092 A 20010824

Abstract (en)

[origin: WO03018880A1] The invention concerns an aqueous electrolytic solution for electrochemical deposition of gold or of its alloys comprising at least a soluble gold compound designed for electrolytic deposition and, optionally at least a secondary metal compound designed for co-deposition in the form of a gold alloy. The invention is characterised in that it further comprises 0.3 to 3 moles per mole of gold contained in the electrolytic solution of an organic compound comprising one or two aldehyde functions, said organic compound being: either glyoxal, or an organic compound comprising 3 to 20 carbon atoms and one or two aldehyde functions in the form: of a saturated or unsaturated, linear or branched aliphatic group, or a group containing at least a saturated, unsaturated or aromatic cycle, said organic compound may further include at least a heteroelement selected among oxygen, nitrogen, sulphur and phosphorus or be in the form of a salt, in particular a sulphonate. The presence of said organic compound enables to increase the speed of electrodeposition of gold or of its alloys and/or to decrease contact resistance. The invention also concerns a method for electrodeposition of gold or of a gold alloy comprising electrolysis of such an electrolytic solution.

IPC 1-7

C25D 3/48; **C25D 3/62**

IPC 8 full level

C25D 3/48 (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP US)

C25D 3/48 (2013.01 - EP US); **C25D 3/62** (2013.01 - EP US)

Citation (search report)

See references of WO 03018880A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SK TR

DOCDB simple family (publication)

WO 03018880 A1 20030306; AT E285489 T1 20050115; CN 1561407 A 20050105; DE 60202378 D1 20050127; DE 60202378 T2 20051208; EP 1423557 A1 20040602; EP 1423557 B1 20041222; FR 2828889 A1 20030228; FR 2828889 B1 20040507; US 2004195107 A1 20041007

DOCDB simple family (application)

FR 0202922 W 20020822; AT 02774881 T 20020822; CN 02819194 A 20020822; DE 60202378 T 20020822; EP 02774881 A 20020822; FR 0111092 A 20010824; US 48583004 A 20040322